SLOVENSKI STANDARD
oSIST prEN IEC 61189-3-720:2026

01-februar-2026

Preskusne metode za električne materiale, tiskana vezja ter druge povezovalne strukture in sestave - 3-720. del: Preskusne metode za povezovalne strukture (tiskana vezja) - Preskusna metoda za določanje prenosnih izgub pri visokofrekvenčnih večplastnih tiskanih vezjih

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3-720: Test methods for interconnection structures (circuit boards) - Transmission loss test method for high frequency multilayer circuit boards

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Ta slovenski standard je istoveten z: **prEN IEC 61189-3-720:2025**

ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards

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91/2081/CDV

COMMITTEE DRAFT FOR VOTE (CDV)

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SECRETARIAT: Japan	SECRETARY: Mr Osamu IKEDA
OF INTEREST TO THE FOLLOWING COMMITTEES:	HORIZONTAL FUNCTION(S):
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TITLE:

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3-720: Test methods for interconnection structures (circuit boards) - Transmission loss test method for high frequency multilayer circuit boards

PROPOSED STABILITY DATE: 2030

NOTE FROM TC/SC OFFICERS:

Approved in WG.

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